

Amendments to the Claims

Please add new claims 40-47 and amend the claims as follows:

1-22. (Canceled)

23. (Currently Amended) A method of supplying a polishing fluid to a chemical mechanical polishing surface comprising:

flowing polishing fluid onto a first portion of a rotating polishing pad at a first rate;
and

flowing polishing fluid of equal concentration on a second portion of the polishing pad at a second rate that is different than the first rate, wherein the polishing fluid disposed on the first portion has a greater volume as it interfaces with a substrate being polished than the polishing fluid disposed on the second portion;

monitoring a thickness of a surface film on the substrate, the monitoring comprising reflecting a beam from the surface film; and

adjusting the flowing of polishing fluid to the first portion and the second portion based upon the monitoring.

24. (Original) The method of claim 23, wherein the first rate is independently controllable relative the second rate.

25. (Previously Presented) The method of claim 23 further comprising:

flowing the polishing fluid on the pad at one or more locations between the first portion and the second portion.

26. (Original) The method of claim 23, wherein the step of flowing the polishing fluid at a first rate further comprises:

adjusting the flow rate during polishing.

27. (Original) The method of claim 26, wherein the step of adjusting further comprises:

adjusting the flow rate in response to a polishing metric.

30-39. (Canceled)

40. (New) The method of claim 23, wherein the polishing pad further comprises:
a window.

41. (New) The method of claim 40, wherein the monitoring further comprises:
emitting a beam through the window to the substrate.

42. (New) A method of supplying a polishing fluid to a chemical mechanical polishing surface comprising:

flowing a polishing fluid to a substrate;

adjusting the flow of polishing fluid to the substrate over a polishing sequence,
the adjusting comprising:

providing more polishing fluid to a center of the substrate as compared to
a perimeter of the substrate; and then

providing more polishing fluid to the perimeter of the substrate as
compared to the center of the substrate.

43. (New) The method of claim 42, wherein the step of adjusting further comprises:
adjusting the flow rate in response to a polishing metric.

44. (New) A method of supplying a polishing fluid to a chemical mechanical polishing surface comprising:

detecting a polishing metric of a surface film being polishing on a substrate with a
polishing fluid, the detecting comprising passing a beam through a window in a
polishing pad and reflecting the beam back to a sensor; and

adjusting a distribution of the polishing fluid to the substrate based upon the monitoring.

45. (New) The method of claim 44, wherein the adjusting further comprises:
providing different amounts of polishing fluid to at least two portions of the polishing pad at different flow rates.
46. (New) The method of claim 44, wherein the adjusting occurs during a polishing process.
47. (New) The method of claim 44, wherein the monitoring further comprises:
emitting a beam through the window to the substrate.